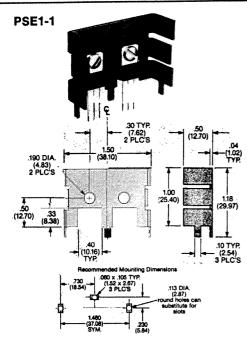### Stand-up, dual-mounted heat dissipators

- Thermally matches two semiconductors within 2°C at equivalent power levels up to 9 watts per semiconductor, permitting paired semiconductors to function more nearly identical.
- Effective alternative to back-to-back semiconductor mounting; eliminates lead interferences.
- Minimizes board space requirements while providing effective heat dissipation.
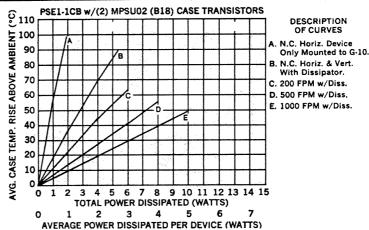- Bend relief notches on mounting tabs permit easy installation with no mounting hardware or special tools required.
- Each dissipator of this series is specifically designed for use with a particular transistor case type — performance and fit are optimized.

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## PSE1-1



.30 TYP. (7.62) 2 PLC'S
.50 (12.70)
1.50 (38.10)
.04 (1.02) TYP.
.190 DIA. (4.83) 2 PLC'S
1.00 (25.40)
1.18 (29.97)
.50 (12.70)
.33 (8.38)
.40 (10.16) TYP.
.10 TYP. (2.54) 3 PLC'S

Recommended Mounting Dimensions
.730 (18.54)
.060 x .105 TYP. (1.52 x 2.67) 3 PLC'S
.113 DIA. (2.87) round holes can substitute for slots
1.460 (37.08) SYM.
.230 (5.84)

Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.

### PSE1-1CB w/(2) MPSU02 (B18) CASE TRANSISTORS



AVG. CASE TEMP. RISE ABOVE AMBIENT (°C)
TOTAL POWER DISSIPATED (WATTS)
AVERAGE POWER DISSIPATED PER DEVICE (WATTS)

DESCRIPTION OF CURVES

A. N.C. Horiz. Device Only Mounted to G-10.
B. N.C. Horiz. & Vert. With Dissipator.
C. 200 FPM w/Diss.
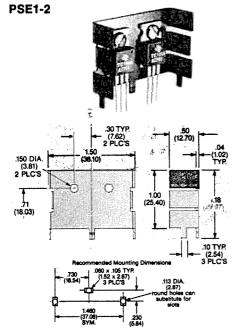D. 500 FPM w/Diss.
E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 1.9-2.3 °C/W w/Joint Compound.
- Derate 6.4 °C/watt per device for unplated part in natural convection only.
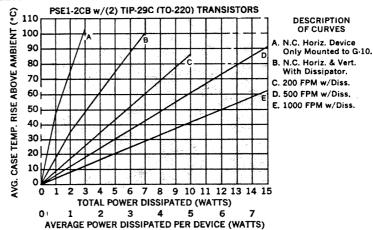- Case Temperatures Match Within 2°C at equivalent power levels.

### Ordering Information

| IERC PART NO. | | | | | Semiconductor Accommodated | Max. Weight (Grams) |
|---|---|---|---|---|---|---|
| Unplated | Comm'l. Black Anodize | Mil. Black Anodize | Nickel | Black Coating with Solderable Tabs | | |
| PSE1-1U | PSE1-1CB | PSE1-1B | PSE1-1ND | PSE1-1TCB | Two Motorola Case 152s | 3.6 |

Note: See page iv for other finishes.

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## PSE1-2



.30 TYP. (7.62) 2 PLC'S
.50 (12.70)
1.50 (38.10)
.04 (1.02) TYP.
.150 DIA. (3.81) 2 PLC'S
1.00 (25.40)
.18
.71 (18.03)
.10 TYP. (2.54) 3 PLC'S

Recommended Mounting Dimensions
.730 (18.54)
.060 x .105 TYP. (1.52 x 2.67) 3 PLC'S
.113 DIA. (2.87) round holes can substitute for slots
1.460 (37.08) SYM.
.230 (5.84)

Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.

### PSE1-2CB w/(2) TIP-29C (TO-220) TRANSISTORS



AVG. CASE TEMP. RISE ABOVE AMBIENT (°C)
TOTAL POWER DISSIPATED (WATTS)
AVERAGE POWER DISSIPATED PER DEVICE (WATTS)

DESCRIPTION OF CURVES

A. N.C. Horiz. Device Only Mounted to G-10.
B. N.C. Horiz. & Vert. With Dissipator.
C. 200 FPM w/Diss.
D. 500 FPM w/Diss.
E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 4.0 °C/watt per device for unplated part in natural convection only.
- Case Temperatures Match Within 2°C at equivalent power levels.

### Ordering Information

| IERC PART NO. | | | | | Semiconductor Accommodated | Max. Weight (Grams) |
|---|---|---|---|---|---|---|
| Unplated | Comm'l. Black Anodize | Mil. Black Anodize | Nickel | Black Coating with Solderable Tabs | | |
| PSE1-2U | PSE1-2CB | PSE1-2B | PSE1-2ND | PSE1-2TCB | Two TO-126s, Two TO-127s, Two TO-220s | 4.2 |

Note: See page iv for other finishes.